

HVD131

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0424-0200 (Previous: ADE-208-832A) Rev.2.00 Oct 29, 2004

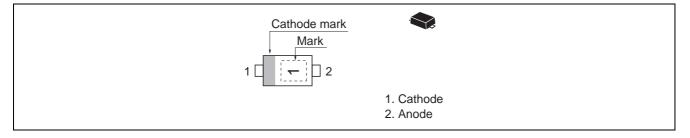
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward resistance. (rf = $1.0 \Omega \text{ max}$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD131	1	SFP

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM}	65	V
Reverse voltage	V _R	60	V
Forward current	IF	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

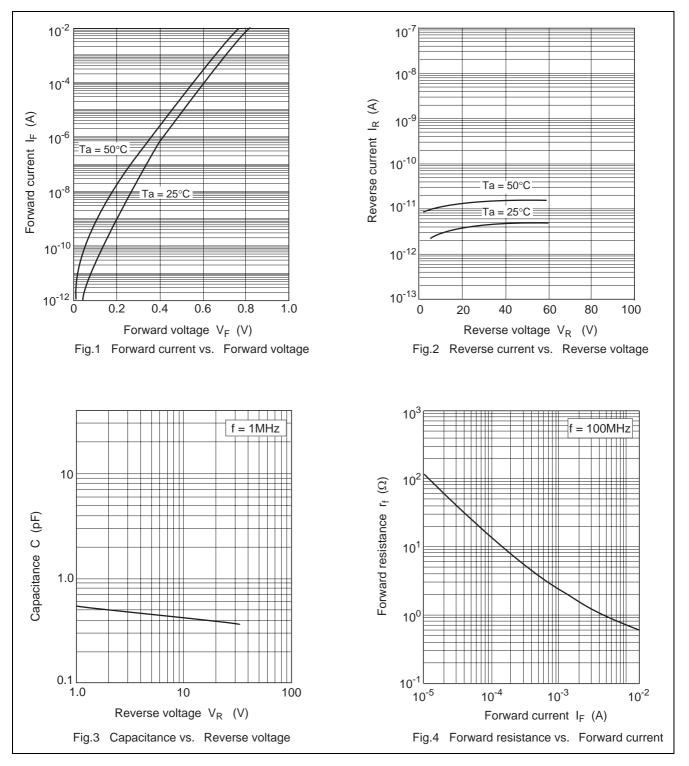
(Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	—	-	0.1	μA	V _R = 60 V
Forward voltage	V _F	—	-	1.0	V	I _F = 10 mA
Capacitance	С	—	-	0.8	pF	$V_R = 1 V, f = 1 MHz$
Forward resistance	r _f	_		1.0	Ω	I _F = 10 mA, f = 100 MHz

Note: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

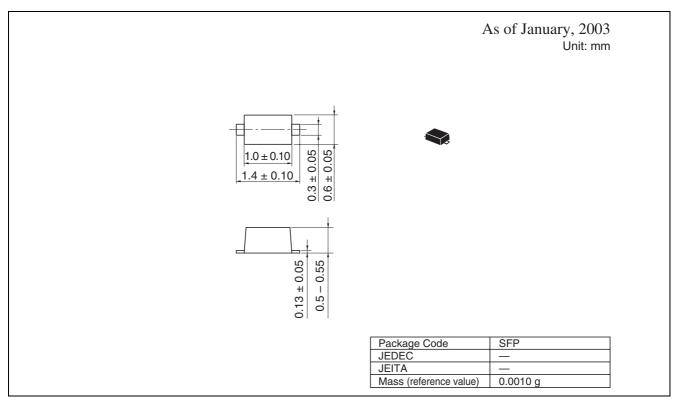


Main Characteristic





Package Dimensions





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